

Session Program

2-6 Jun 2025



3rd DRD3 week on Solid State Detectors R&D ***WG7/WP7 - Interconnect technologies***

Nikhef, Amsterdam

Friday 6 June

10:50

WG7/WP7 - Interconnect technologies

Session | **Location:** Nikhef, Amsterdam

10:50–10:55 **Introduction**

Speakers

Calderini, G., Dominik Dannheim, Fabian Huegging, Giovanni Calderini

10:55–11:15 **In-house plating updates**

Speaker

Moritz Lauser

11:15–11:35 **In-house Flip-Chip Hybridisation Updates**

Speaker

Dr Ahmet Lale

11:35–11:55

Towards Ultra-Lightweight and Flexible Pixel Modules - First Prototype and Performance Results

Speaker

Julian Weick

11:55–12:15

MAPS Integration with Flexible and Low-Material-Budget Electronics

Speaker

David Novel

12:15–12:35

Development of ultra-thin hybrid pixel detectors using Wafer-to-Wafer bonding

Speaker

Fabian Huegging

12:35–12:50

Discussion

12:50